



TPMNB250

Pb RoHS

20V N-Channel MOSFETs

General Description

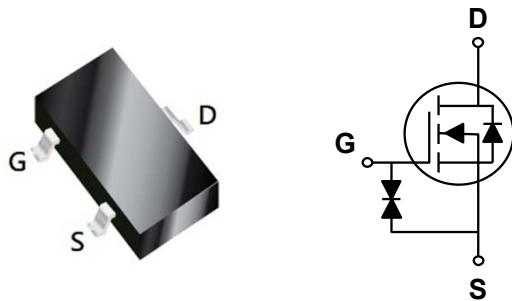
These N-Channel enhancement mode power field effect transistors are using trench DMOS technology. This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficiency fast switching applications.

BV_{DSS}	$R_{DS(ON)}$	I_D
20 V	250 mΩ	0.8 A

Features

- $R_{DS(ON)} \leq 250\text{m}\Omega @ V_{GS}=4.5\text{V}$
- Improved dv/dt Capability
- Fast Switching
- Green Device Available
- ESD Protection

SOT-323 Pin Configuration



Applications

- Power Management in DC/DC Converters
- Power Load Switch
- Notebook Battery Management

Absolute Maximum Ratings $T_J=25^\circ\text{C}$ unless otherwise noted

Symbol	Parameter	Rating	Units
V_{DS}	Drain-Source Voltage	20	V
V_{GS}	Gate-Source Voltage	± 12	V
I_D	Drain Current - Continuous ($T_A=25^\circ\text{C}$)	0.8	A
I_{DM}	Drain Current - Pulsed ($T_A=25^\circ\text{C}$) (NOTE 1)	1.8	A
P_D	Power Dissipation ($T_A=25^\circ\text{C}$)	0.26	W
T_J	Operating Junction Temperature Range	-50 to 150	$^\circ\text{C}$
T_{STG}	Storage Temperature Range	-50 to 150	$^\circ\text{C}$
Marking Code		0	

Thermal Characteristics

Symbol	Parameter	Rating	Unit
$R_{\theta JA}$	Thermal Resistance Junction to Ambient	480	$^\circ\text{C}/\text{W}$



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Electrical Characteristics ($T_J=25^\circ\text{C}$, unless otherwise noted)

Off Characteristics

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
BV_{DSS}	Drain-Source Breakdown Voltage	$V_{\text{GS}}=0\text{V}$, $I_D=250\mu\text{A}$	20	---	---	V
I_{DSS}	Drain-Source Leakage Current	$V_{\text{DS}}=16\text{V}$, $V_{\text{GS}}=0\text{V}$	---	---	1	μA
I_{GSS}	Gate-Source Leakage Current	$V_{\text{GS}}=\pm 12\text{V}$, $V_{\text{DS}}=0\text{V}$	---	---	± 10	μA

On Characteristics

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$R_{\text{DS}(\text{ON})}$	Static Drain-Source On-Resistance	$V_{\text{GS}}=4.5\text{V}$, $I_D=0.4\text{A}$	---	---	250	$\text{m}\Omega$
		$V_{\text{GS}}=2.5\text{V}$, $I_D=0.25\text{A}$	---	---	360	
		$V_{\text{GS}}=1.8\text{V}$, $I_D=0.15\text{A}$	---	---	580	
$V_{\text{GS}(\text{th})}$	Gate Threshold Voltage	$V_{\text{GS}}=V_{\text{DS}}$, $I_D=250\mu\text{A}$	0.5	---	1.0	V
g_{fs}	Forward Transconductance	$V_{\text{DS}}=3\text{V}$, $I_{\text{DS}}=0.2\text{A}$	---	0.9	---	S

Dynamic and switching Characteristics (NOTE 3)

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
Q_g	Total Gate Charge	$V_{\text{DS}}=10\text{V}$, $V_{\text{GS}}=4.5\text{V}$, $I_D=1\text{A}$	---	1	---	nC
Q_{gs}	Gate-Source Charge		---	0.3	---	
Q_{gd}	Gate-Drain Charge		---	0.1	---	
$T_{\text{d}(\text{on})}$	Turn-On Delay Time	$V_{\text{DS}}=10\text{V}$, $V_{\text{GS}}=4.5\text{V}$, $R_{\text{GEN}}=60\Omega$, $I_D=2\text{A}$	---	1.2	---	nS
T_r	Rise Time		---	24.6	---	
$T_{\text{d}(\text{off})}$	Turn-Off Delay Time		---	13.6	---	
T_f	Fall Time		---	14.6	---	
C_{iss}	Input Capacitance	$V_{\text{DS}}=10\text{V}$, $V_{\text{GS}}=0\text{V}$, $F=1\text{MHz}$	---	40	---	pF
C_{oss}	Output Capacitance		---	17	---	
C_{rss}	Reverse Transfer Capacitance		---	10	---	
R_g	Gate Resistance	$V_{\text{DS}}=10\text{V}$, $V_{\text{GS}}=0\text{V}$, $F=1\text{MHz}$	---	195	---	Ω

Drain-Source Diode Characteristics and Ratings

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
V_{SD}	Diode Forward Voltage	$V_{\text{GS}}=0\text{V}$, $I_S=0.2\text{A}$	---	---	1.1	V
t_{rr}	Reverse Recovery Time	$I_F=1\text{A}$, $V_R=10\text{V}$, $dI_F/dt=100\text{A}/\mu\text{s}$	---	9.2	---	nS
Q_{rr}	Reverse Recovery Charge		---	0.8	---	nC

NOTES :

1. Repetitive Rating : Pulsed width limited by maximum junction temperature.
2. The data tested by pulsed , pulse width $\leq 300\mu\text{s}$, duty cycle $\leq 2\%$.
3. Guaranteed by design, not subject to production testing



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Characteristics Curves

FIG. 1-Drain Current

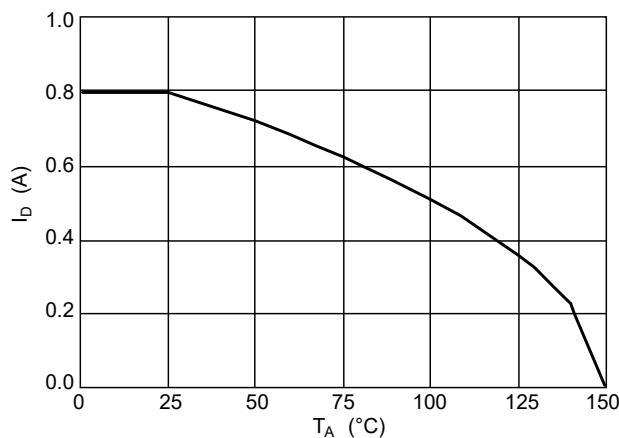


FIG. 2-Normalized R_{DS(ON)} vs T_J

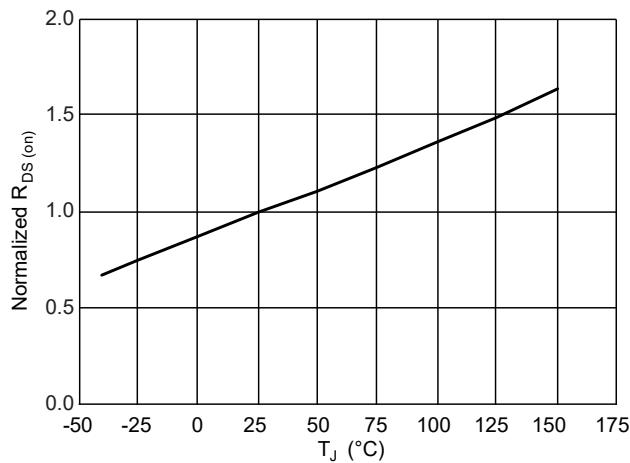


FIG. 5-Safe Operating Area

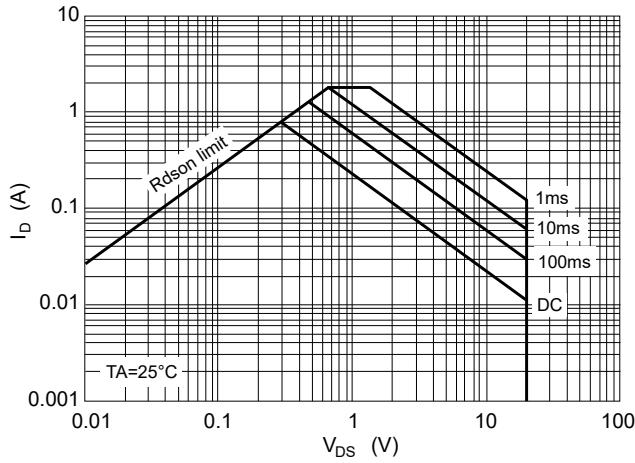


FIG. 2-Normalized V_{GS(th)} vs T_J

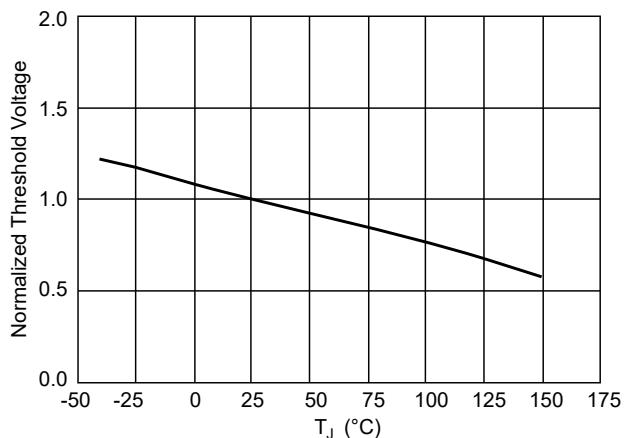


FIG. 4-Gate Charge Characteristics

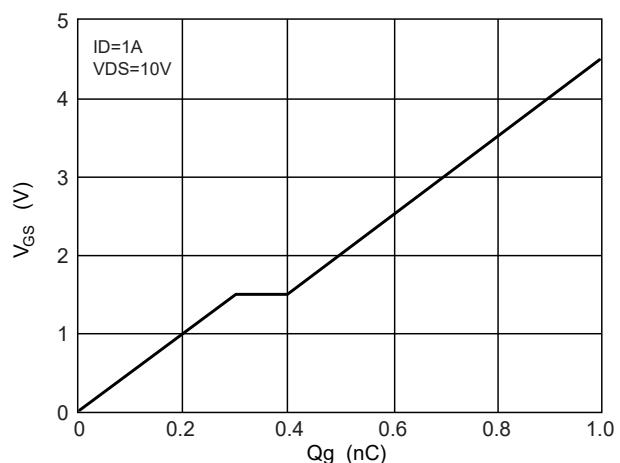
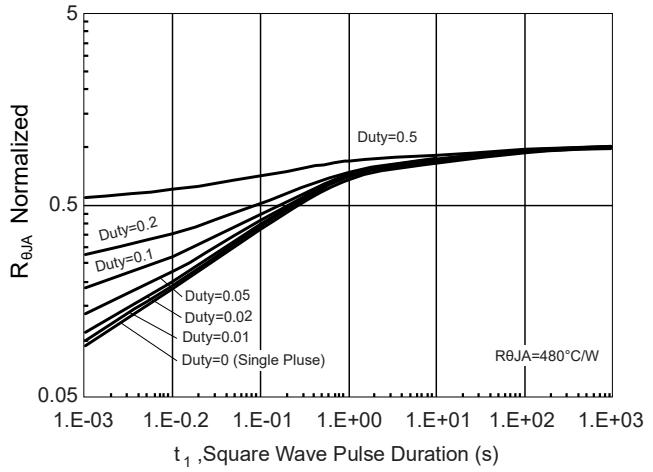


FIG. 6-Transient Thermal Impedance



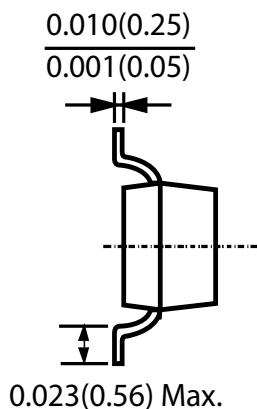
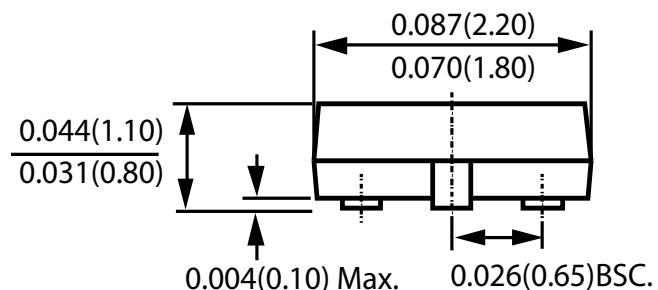
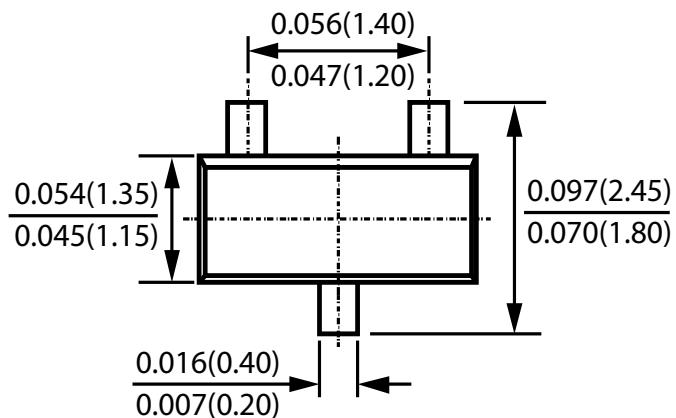


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Package Outline Dimensions



SOT-323

Dimensions in inches and (millimeters)



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